

15 at least one cylinder lifting/lowering mechanism per one
said cylinder is provided, in order to separate a space inside
said cylinder [composing] comprising a processing chamber for
processing said substrate surface from a space outside said
cylinder [composing] including a transport chamber for
transferring said substrate;

20 said transport chamber [is] provided with a substrate
conveyer mechanism for transferring said substrate between said
processing chamber and said transport chamber through said gap;

CMIA 2 21 said processing chamber is provided with a processing
chamber gas inlet and a processing chamber gas outlet; and

26 said transport chamber is provided with a transport chamber
gas inlet and a transport chamber gas outlet.

2. (Amended) A semiconductor manufacturing apparatus for
processing a substrate surface, the apparatus[,] composed of a
vacuum vessel with a top and bottom plate, said apparatus
comprising: [; wherein,]

5 a plurality of substrate stages are provided on said vacuum
vessel bottom plate;

10 cylinders provided respectively with an O ring are connected
to said bottom plate through a bellows so as to surround said
substrate stage said cylinders forming a gap with said vacuum
vessel top plate;

the gap between said cylinder and said vacuum vessel top plate is made variable by lifting/lowering said cylinder, and at a position where said gap becomes minimum, a plurality of cylinder lifting/lowering mechanisms per one said cylinder are provided, in order to hermetically separate [separate hermetically] a space inside said cylinder for creating [composing] a processing chamber for processing said substrate surface with said O ring from a space outside said cylinder for creating [composing] a transport chamber for transferring said substrate;

20 said transport chamber is provided with a substrate conveyer mechanism for transferring said substrate between said processing chamber and said transport chamber through said gap;

25 said processing chamber is provided with a processing chamber gas inlet and a processing chamber gas outlet; and

30 said transport chamber is provided with a transport chamber gas inlet and a transport chamber gas outlet.

Claim 3, line 2 please delete "or 2".

Claim 4, line 2 please delete "and claim 3" and replace it with --further--.

3 7. The semiconductor manufacturing apparatus according to [any one of Claims 1 to 6] Claim 2, wherein said substrate stage